



## TPD4E1U06 Quad-Channel, High-Speed ESD Protection Device

### 1 Features

- IEC 61000-4-2 Level 4 ESD Protection
  - $\pm 15$ -kV Contact Discharge
  - $\pm 15$ -kV Air-Gap Discharge
- IEC 61000-4-4 EFT Protection
  - 80 A (5/50 ns)
- IEC 61000-4-5 Surge Protection
  - 3 A (8/20  $\mu$ s)
- IO Capacitance 0.8 pF (Typical)
- DC Breakdown Voltage 6.5 V (Minimum)
- Ultra Low Leakage Current 10 nA (Maximum)
- Low ESD Clamping Voltage
- Industrial Temperature Range:  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$
- Small, Easy-to-Route DCK, and DBV Package

### 2 Applications

- USB 2.0
- Ethernet
- HDMI Control Lines
- MIPI Bus
- LVDS
- SATA

### 3 Description

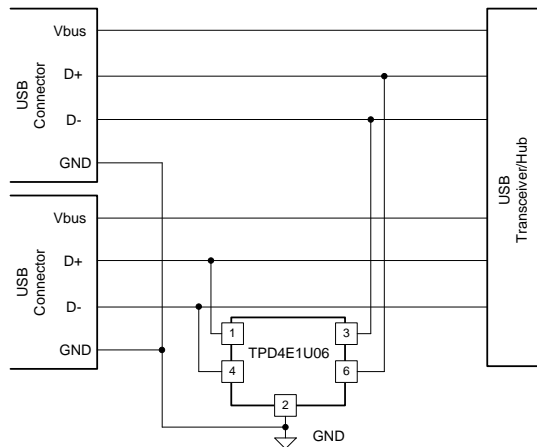
The TPD4E1U06 is a quad-channel unidirectional Transient Voltage Suppressor (TVS) based Electrostatic Discharge (ESD) protection diode with ultra low capacitance. This device can dissipate ESD strikes above the maximum level specified by the IEC 61000-4-2 international standard. Its 0.8-pF line capacitance makes it suitable for a wide range of applications. Typical application areas include HDMI, USB2.0, MHL, and DisplayPort.

#### Device Information<sup>(1)</sup>

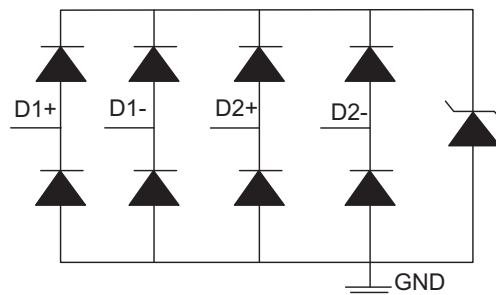
PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPD4E1U06DCK	SC70	2.00 mm $\times$ 1.25 mm
TPD4E1U06DBV	SOT-23	2.90 mm $\times$ 1.60 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

**Simplified Schematic**



**Circuit Schematic Diagram**



## Table of Contents

<b>1 Features</b> .....	<b>1</b>	7.4 Device Functional Modes.....	<b>9</b>
<b>2 Applications</b> .....	<b>1</b>	<b>8 Application and Implementation</b> .....	<b>10</b>
<b>3 Description</b> .....	<b>1</b>	8.1 Application Information.....	<b>10</b>
<b>4 Revision History</b> .....	<b>2</b>	8.2 Typical Application .....	<b>10</b>
<b>5 Pin Configuration and Functions</b> .....	<b>3</b>	<b>9 Power Supply Recommendations</b> .....	<b>12</b>
<b>6 Specifications</b> .....	<b>4</b>	<b>10 Layout</b> .....	<b>12</b>
6.1 Absolute Maximum Ratings .....	4	10.1 Layout Guidelines .....	12
6.2 ESD Ratings.....	4	10.2 Layout Example .....	12
6.3 ESD Ratings—IEC Specification .....	4	<b>11 Device and Documentation Support</b> .....	<b>13</b>
6.4 Recommended Operating Conditions.....	4	11.1 Documentation Support .....	13
6.5 Thermal Information .....	4	11.2 Receiving Notification of Documentation Updates .....	13
6.6 Electrical Characteristics.....	5	11.3 Community Resources.....	13
6.7 Typical Characteristics .....	6	11.4 Trademarks .....	13
<b>7 Detailed Description</b> .....	<b>8</b>	11.5 Electrostatic Discharge Caution.....	13
7.1 Overview .....	8	11.6 Glossary .....	13
7.2 Functional Block Diagram .....	8	<b>12 Mechanical, Packaging, and Orderable Information</b> .....	<b>13</b>
7.3 Feature Description.....	8		

## 4 Revision History

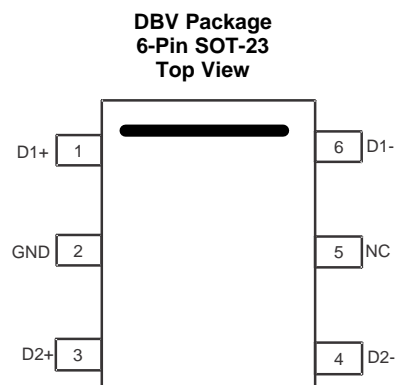
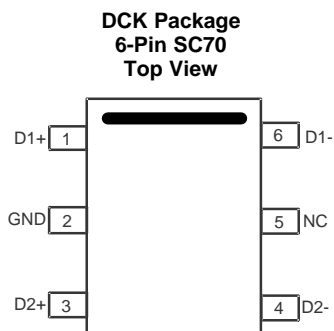
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision C (October 2014) to Revision D</b>	<b>Page</b>
• Updated DCK and DBV Pinout image .....	<b>3</b>
• Added 61000-4-5 spec to <i>Absolute Maximum Ratings</i> table .....	<b>4</b>
• Added <i>IEC 61000-4-5 Surge Protection</i> section .....	<b>8</b>
• Added <i>IEC 61000-4-4 EFT Protection</i> section .....	<b>8</b>

<b>Changes from Revision B (February 2013) to Revision C</b>	<b>Page</b>
• Added <i>Pin Configuration and Functions</i> section, <i>Handling Rating</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	<b>1</b>

<b>Changes from Revision A (December 2012) to Revision B</b>	<b>Page</b>
• Added C <sub>CROSS</sub> data for DBV package.....	<b>5</b>

## 5 Pin Configuration and Functions



### Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
D1+	1	I/O	ESD protected channel. Connect to data line as close to the connector as possible
D1–	6	I/O	
D2–	4	I/O	
D2+	3	I/O	Ground. Connect to ground
GND	2	GND	
NC	5	I/O	

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
	IEC 61000-4-4 EFT protection (5/50 ns)		80	A
I <sub>PP</sub>	IEC 61000-4-5 surge protection (8/20 μs) peak pulse current		3	A
P <sub>PP</sub>	IEC 61000-4-5 surge protection (8/20 μs) peak pulse power		45	W
	Operating temperature	–40	125	°C
T <sub>stg</sub>	Storage temperature	–65	115	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub> Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±4000	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±1500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 ESD Ratings—IEC Specification

		VALUE	UNIT
V <sub>(ESD)</sub> Electrostatic discharge	IEC 61000-4-2 contact ESD	±15000	V
	IEC 61000-4-2 air-gap ESD	±15000	

### 6.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>IO</sub>	Input pin voltage	0	5.5	V
T <sub>A</sub>	Operating free-air temperature	–40	125	°C

### 6.5 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TPD4E1U06		UNIT
		DBV (SOT-23)	DCK (SC-70)	
		6 PINS	6 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	224.3	274.3	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	166.1	113.8	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	68.4	76.7	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	57.3	3.6	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	67.9	75.9	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.6 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{RWM}$	Reverse stand-off voltage $I_{IO} = 10 \mu A$			5.5	V
$V_{CLAMP}$	Clamp voltage with ESD strike $I_{PP} = 1 A$ , $t_p = 8/20 \mu s$ , from I/O to GND <sup>(1)</sup>		11		V
	$I_{PP} = 3 A$ , $t_p = 8/20 \mu s$ , from I/O to GND <sup>(1)</sup>		15		V
$R_{DYN}$	Dynamic resistance Pin x to GND pin <sup>(2)</sup>		1.0		$\Omega$
	GND to pin x		0.6		
$C_L$	Line capacitance $f = 1 MHz$ , $V_{BIAS} = 2.5 V$ , $25^\circ C$		0.8	1	pF
$C_{CROSS}$	Channel to channel input capacitance Pin 2 = 0 V, $f = 1 MHz$ , $V_{BIAS} = 2.5 V$ , between channel pins	DCK package	0.006	0.015	pF
		DBV package	0.01	0.025	
$\Delta C_{IO-TO-GND}$	Variation of channel input capacitance Pin 2 = 0 V, $f = 1 MHz$ , $V_{BIAS} = 2.5 V$ , channel_x pin to ground – channel_y pin to ground		0.025	0.07	pF
$V_{BR}$	Break-down voltage, IO to GND $I_{IO} = 1 mA$	6.5		8.5	V
$I_{LEAK}$	Leakage current $V_{IO} = 2.5 V$		1	10	nA

(1) Non-repetitive current pulse 8/20  $\mu s$  exponentially decaying waveform according to IEC61000-4-5.

(2) Extraction of  $R_{DYN}$  using least squares fit of TLP characteristics between  $I = 10 A$  and  $I = 20 A$ .

## 6.7 Typical Characteristics

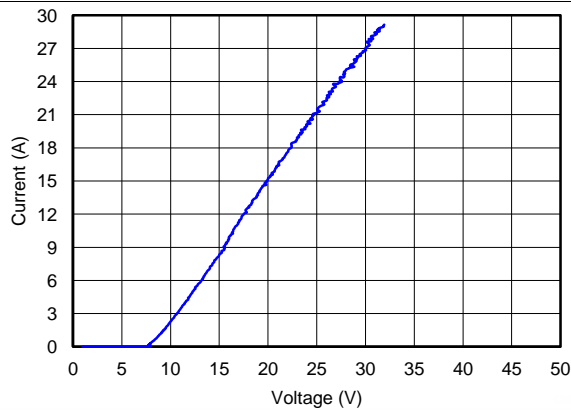


Figure 1. TLP, Data to GND

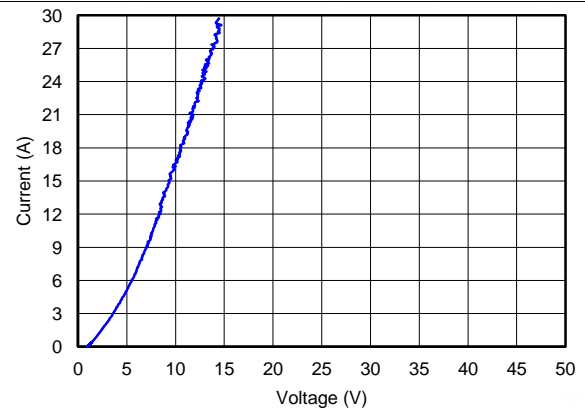


Figure 2. TLP, GND to Data

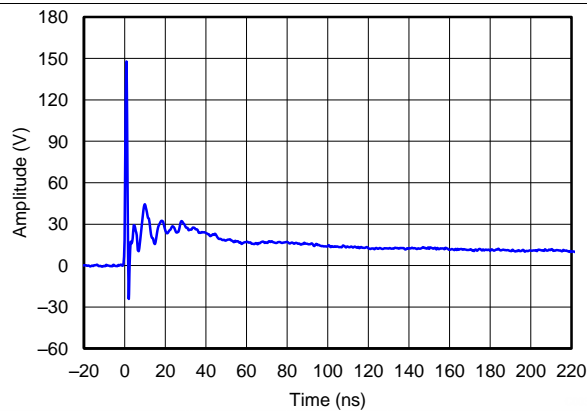


Figure 3. IEC 61000-4-2 Clamping Voltage, 8-kV Contact

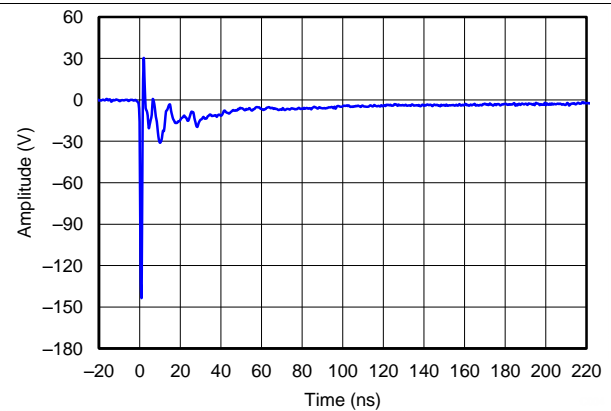


Figure 4. IEC 61000-4-2 Clamping Voltage, -8-kV Contact

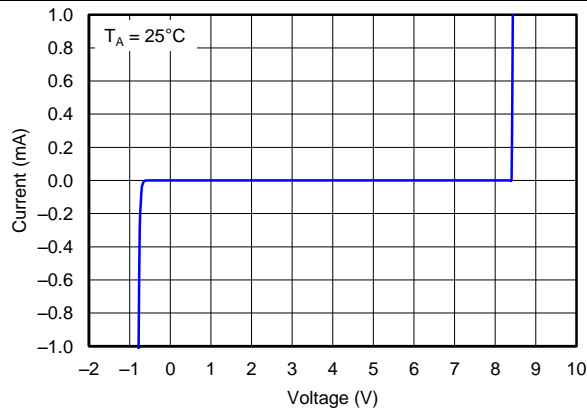


Figure 5. Diode Curve

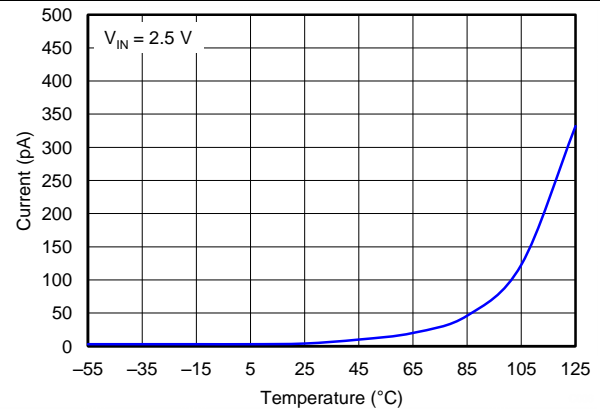
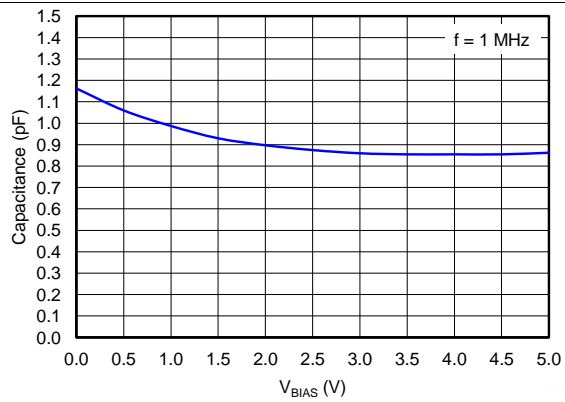
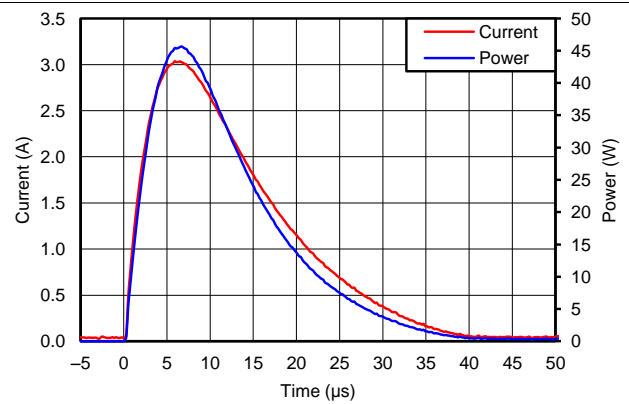


Figure 6.  $I_{LEAK}$  vs Temperature

## Typical Characteristics (continued)



**Figure 7. Capacitance Across V<sub>BIAS</sub>**



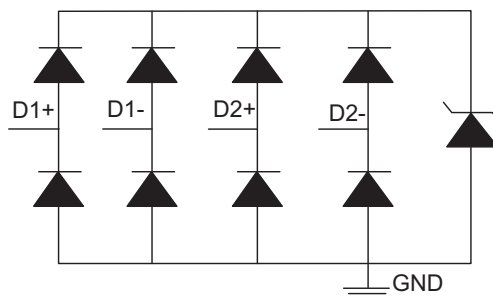
**Figure 8. Surge Curve (tp = 8/20 μs), Pin IO to GND**

## 7 Detailed Description

### 7.1 Overview

The TPD4E1U06 is a quad channel unidirectional TVS ESD protection diode with ultra low capacitance. This device can dissipate ESD strikes above the maximum level specified by the IEC 61000-4-2 international standard. Typical application areas include HDMI, USB2.0, MHL, and DisplayPort. Its 0.8-pF line capacitance makes it suitable for a wide range of applications.

### 7.2 Functional Block Diagram



**Figure 9. Circuit Schematic Diagram**

### 7.3 Feature Description

#### 7.3.1 IEC 61000-4-2 Level 4 ESD Protection

The I/O pins can withstand ESD events up to  $\pm 15$ -kV contact and air. An ESD/surge clamp diverts the current to ground.

#### 7.3.2 IEC 61000-4-5 Surge Protection

The IO pins can withstand surge events up to 3 A and 45 W (8/20- $\mu$ s waveform). An ESD-surge clamp diverts this current to ground.

#### 7.3.3 IEC 61000-4-4 EFT Protection

The IO pins can withstand an electrical fast transient burst of up to 80 A (5/50-ns waveform, 4 kV with 50- $\Omega$  impedance). An ESD-surge clamp diverts the current to ground.

#### 7.3.4 IO Capacitance

The capacitance between each I/O pin to ground is 0.8 pF.

#### 7.3.5 DC Breakdown Voltage

The DC breakdown voltage of each I/O pin is a minimum of 6.5 V. This ensures that sensitive equipment is protected from surges above the reverse standoff voltage of 5.5 V.

#### 7.3.6 Ultra Low Leakage Current

The I/O pins feature an ultra-low leakage current of 10 nA (Maximum) with a bias of 2.5 V.

#### 7.3.7 Low ESD Clamping Voltage

The I/O pins feature an ESD clamp that is capable of clamping the voltage to 11 V ( $I_{PP} = 1$  A).

#### 7.3.8 Industrial Temperature Range

This device features an industrial operating range of  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ .



## **Feature Description (continued)**

### **7.3.9 Small, Easy-to-Route Packages**

The layout of this device makes it simple to add protection to the design. Industry standard packages allow for easy additions to the board and easy layout.

## **7.4 Device Functional Modes**

The TPD4E1U06 is a passive integrated circuit that triggers when voltages are above  $V_{BR}$  or below the forward diode drop. During ESD events, voltages as high as  $\pm 15$  kV can be directed to ground via the internal diode network. Once the voltages on the protected line fall below the trigger levels of TPD4E1U06 (usually within 10s of nano-seconds) the device reverts to passive.

## 8 Application and Implementation

### NOTE

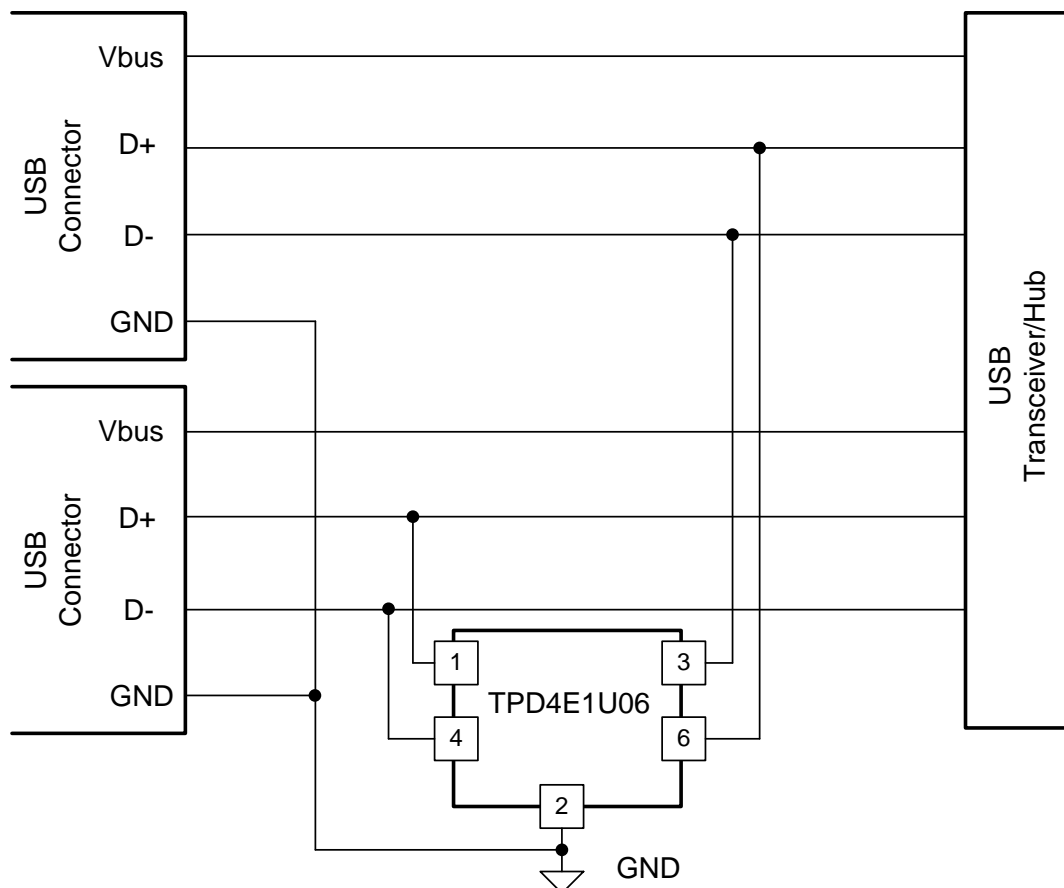
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The TPD4E1U06 is a TVS diode array which is typically used to provide a path to ground for dissipating ESD events on hi-speed signal lines between a human interface connector and a system. As the current from ESD passes through the TVS, only a small voltage drop is present across the diode. This is the voltage presented to the protected IC. The low  $R_{DYN}$  of the triggered TVS holds this voltage,  $V_{CLAMP}$ , to a safe level for the protected IC.

### 8.2 Typical Application

For this design example, one TPD4E1U06 device is being used in a dual USB 2.0 application. This provides a complete port protection scheme.



**Figure 10. Dual USB 2.0 Application**

## Typical Application (continued)

### 8.2.1 Design Requirements

Given the USB 2.0 application, the parameters in [Table 1](#) are known.

**Table 1. Design Parameters**

DESIGN PARAMETER	VALUE
Signal range on pins 1, 3, 4, or 6	0 V to 5 V
Operating frequency	240 MHz

### 8.2.2 Detailed Design Procedure

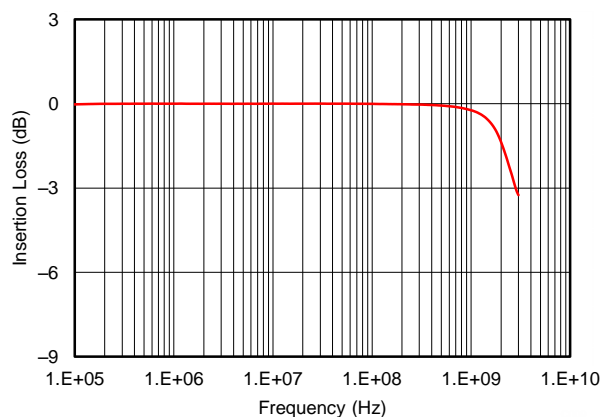
#### 8.2.2.1 Signal Range on Pins 1, 3, 4, or 6

The TPD4E1U06 has 4 identical protection channels for signal lines. The symmetry of the device provides flexibility when selecting which of the 4 I/O channels protect which signal lines. Any I/O supports a signal range of 0 to 5.5 V.

#### 8.2.2.2 Operating Frequency

The TPD4E1U06 has a capacitance of 0.8 pF (typical), supporting USB 2.0 data rates.

### 8.2.3 Application Curve



**Figure 11. Insertion Loss Graph**

## 9 Power Supply Recommendations

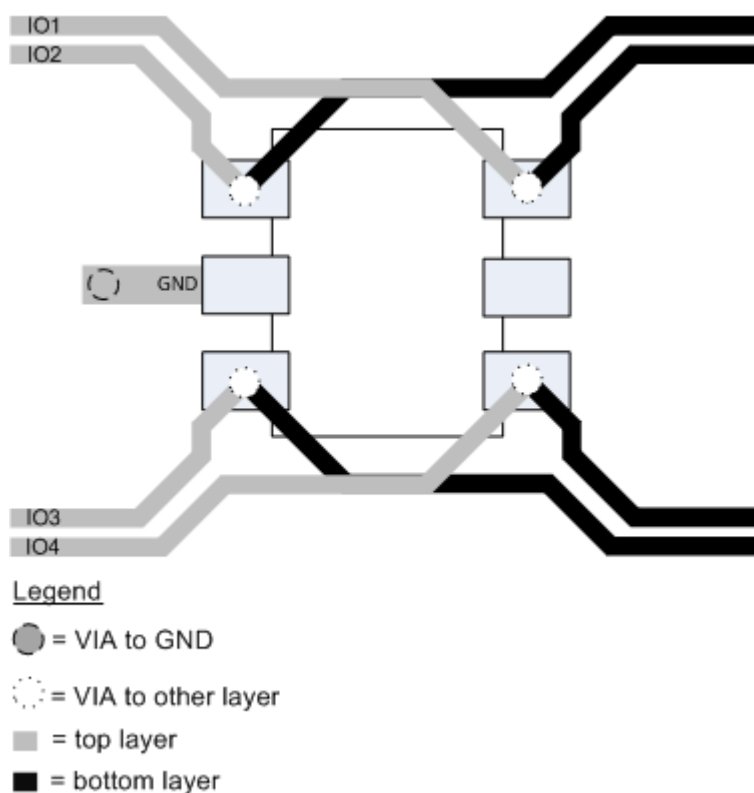
This device is a passive ESD device so there is no need to power it. Take care not to violate the recommended I/O specification (0 V to 5.5 V) to ensure the device functions properly.

## 10 Layout

### 10.1 Layout Guidelines

- The optimum placement is as close to the connector as possible.
  - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
  - The PCB designer needs to minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
  - Electric fields tend to build up on corners, increasing EMI coupling.

### 10.2 Layout Example



**Figure 12. PCB Layout Recommendation**

## 11 Device and Documentation Support

### 11.1 Documentation Support

#### 11.1.1 Related Documentation

For related documentation see the following:

- [Reading and Understanding an ESD Protection Datasheet](#)
- [ESD Layout Guide](#)
- [TPD4E1U06DCK EVM User's Guide](#)
- [TPD4E1U06DBV EVM User's Guide](#)

### 11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates—including silicon errata—go to the product folder for your device on [ti.com](#). In the upper right-hand corner, click the *Alert me* button. This registers you to receive a weekly digest of product information that has changed (if any). For change details, check the revision history of any revised document.

### 11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](#), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 11.4 Trademarks

E2E is a trademark of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 11.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPD4E1U06DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	NG4	<a href="#">Samples</a>
TPD4E1U06DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(BP6 ~ BP8 ~ BPI) (BPH ~ BPI ~ BPP ~ BPS)	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD4E1U06DBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPD4E1U06DCKR	SC70	DCK	6	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
TPD4E1U06DCKR	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3



## TAPE AND REEL BOX DIMENSIONS

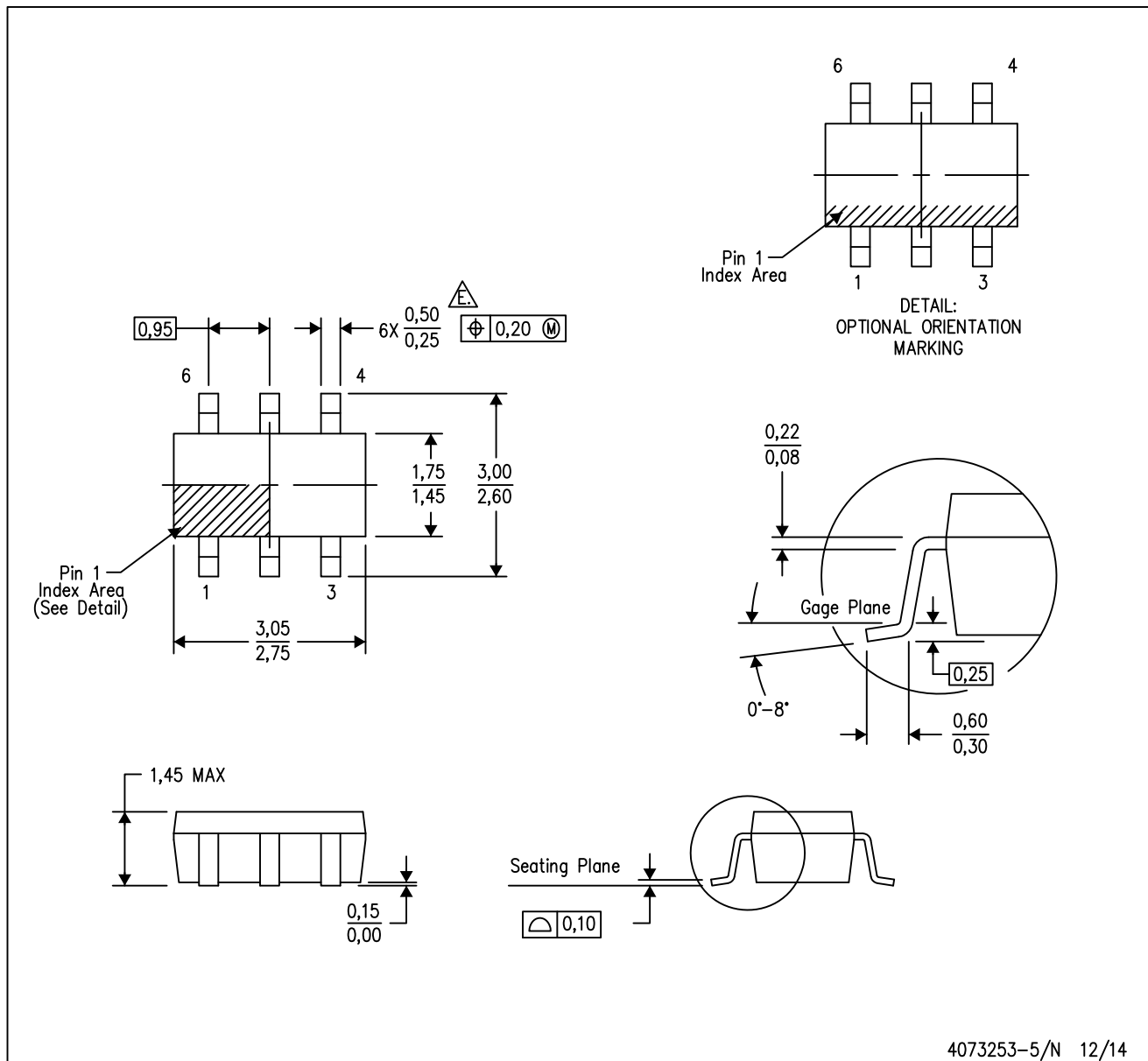


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD4E1U06DBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
TPD4E1U06DCKR	SC70	DCK	6	3000	180.0	180.0	18.0
TPD4E1U06DCKR	SC70	DCK	6	3000	180.0	180.0	18.0

DBV (R-PDSO-G6)

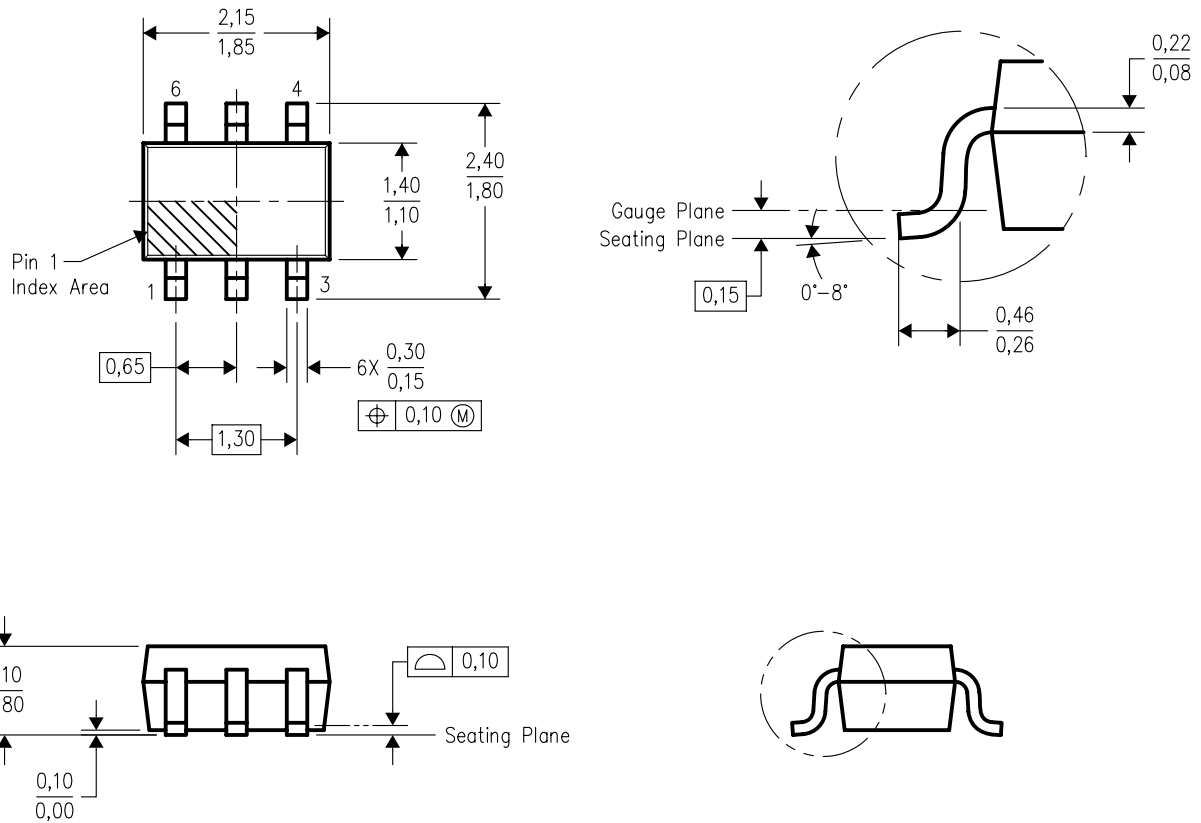
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
  - E. Falls within JEDEC MO-178 Variation AB, except minimum lead width.

## DCK (R-PDSO-G6)

## PLASTIC SMALL-OUTLINE PACKAGE



4093553-4/G 01/2007

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - Falls within JEDEC MO-203 variation AB.

DCK (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

## IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.